TOSHIBA Power Transistor Module Silicon PNP Epitaxial Type (Darlington power transistor 4 in 1)

# **MP4504**

High Power Switching Applications.

Hammer Drive, Pulse Motor Drive and Inductive Load Switching.

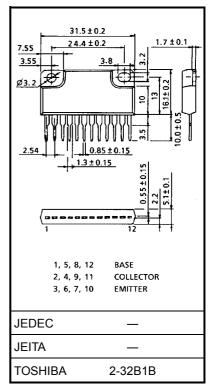
- Package with heat sink isolated to lead (SIP 12 pin)
- High collector power dissipation (4 devices operation) :  $P_T = 5 \text{ W (Ta} = 25^{\circ}\text{C)}$
- High collector current:  $I_{C(DC)} = -5 A \text{ (max)}$
- High DC current gain:  $h_{FE} = 2000$  (min) ( $V_{CE} = -5$  V,  $I_{C} = -3$  A)

#### Maximum Ratings (Ta = 25°C)

Characteristics		Symbol	Rating	Unit	
Collector-base voltage		V <sub>CBO</sub>	-100	V	
Collector-emitter voltage		V <sub>CEO</sub>	-100	V	
Emitter-base voltage		V <sub>EBO</sub>	-6	V	
Collector current	DC	I <sub>C</sub>	-5	А	
	Pulse	I <sub>CP</sub>	-8	A	
Continuous base current		I <sub>B</sub>	-0.5	Α	
Collector power dissipation (1 device operation)		PC	3.0	W	
Collector power dissipation	Ta = 25°C	PT	5.0	W	
(4 devices operation)	Tc = 25°C	' '	25	•	
Isolation voltage		V <sub>Isol</sub>	1000	V	
Junction temperature		Тј	150	°C	
Storage temperature range		T <sub>stg</sub>	-55 to 150	°C	

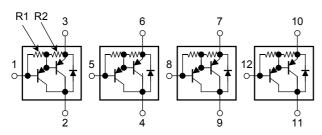
#### **Industrial Applications**

Unit: mm



Weight: 6.0 g (typ.)

### **Array Configuration**



R1  $\approx$  4.5 k $\Omega$ , R2  $\approx$  300  $\Omega$ 



#### **Thermal Characteristics**

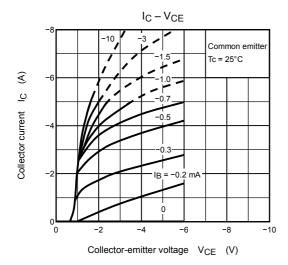
Characteristics	Symbol	Max	Unit	
Thermal resistance of junction to ambient  (4 devices operation, Ta = 25°C)	ΣR <sub>th (j-a)</sub>	25	°C/W	
(+ devices operation, Ta = 25 C)				
Thermal resistance of junction to case	ΣD., ,, ,	5.0	°C/W	
(4 devices operation, Tc = 25°C)	ΣR <sub>th (j-c)</sub>	5.0	C/VV	
Maximum lead temperature for soldering purposes	TL	260	°C	
(3.2 mm from case for 10 s)			İ	

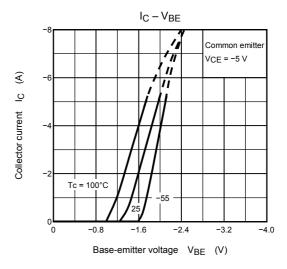
## Electrical Characteristics (Ta = 25°C)

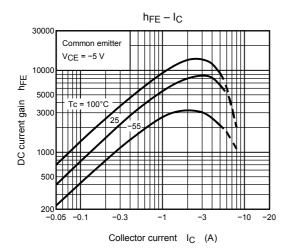
Charac	eteristics	Symbol	Test Condition	Min	Тур.	Max	Unit	
Collector cut-off current		I <sub>CBO</sub>	V <sub>CB</sub> = -100 V, I <sub>E</sub> = 0 A	_	_	-10	μΑ	
Collector cut-off cu	ırrent	I <sub>CEO</sub>	V <sub>CE</sub> = -100 V, I <sub>B</sub> = 0 A	_	_	-10	μΑ	
Emitter cut-off curr	ent	I <sub>EBO</sub>	V <sub>EB</sub> = -6 V, I <sub>C</sub> = 0 A	-0.6	_	-2.0	mA	
Collector-base bre	akdown voltage	V (BR) CBO	I <sub>C</sub> = -1 mA, I <sub>E</sub> = 0 A	-100	_	_	V	
Collector-emitter b	reakdown voltage	V (BR) CEO	I <sub>C</sub> = -10 mA, I <sub>B</sub> = 0 A	-100	_	_	V	
DC current gain		h <sub>FE (1)</sub>	V <sub>CE</sub> = -5 V, I <sub>C</sub> = -3 A	2000	_	15000	_	
		h <sub>FE (2)</sub>	V <sub>CE</sub> = -5 V, I <sub>C</sub> = -5 A	1000	_	_		
Saturation voltage	Collector-emitter	V <sub>CE (sat)</sub>	I <sub>C</sub> = -3 A, I <sub>B</sub> = -6 mA	_	_	-1.5	٧	
	Base-emitter	V <sub>BE (sat)</sub>	$I_C = -3 \text{ A}, I_B = -6 \text{ mA}$	_	_	-2.0		
Transition frequency		f <sub>T</sub>	$V_{CE} = -2 \text{ V}, I_{C} = -0.5 \text{ A}$	_	40	_	MHz	
Collector output capacitance		C <sub>ob</sub>	V <sub>CB</sub> = -10 V, I <sub>E</sub> = 0 A, f = 1 MHz	_	55	_	pF	
Switching time Stor	Turn-on time	t <sub>on</sub>	Output	_	0.3	_		
	Storage time	t <sub>stg</sub>	20 μs B1 W SC	_	2.0	_	μs	
	Fall time	t <sub>f</sub>	$V_{CC} = -30 \text{ V}$ $-I_{B1} = I_{B2} = 6 \text{ mA}, \text{ duty cycle} \le 1\%$	_	0.4	_		

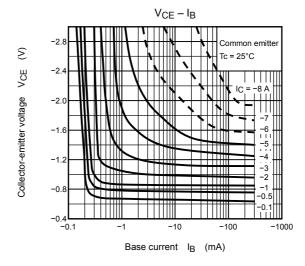
## **Emitter-Collector Diode Ratings and Characteristics (Ta = 25°C)**

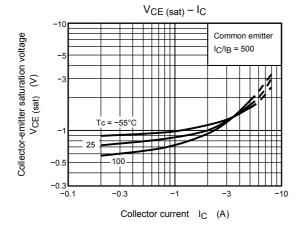
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Forward current	I <sub>FM</sub>	_	_	_	3	Α
Surge current	I <sub>FSM</sub>	t = 1 s, 1 shot	_	_	6	Α
Forward voltage	V <sub>F</sub>	I <sub>F</sub> = 1 A, I <sub>B</sub> = 0 A	_	_	2.0	V
Reverse recovery time	t <sub>rr</sub>	I <sub>F</sub> = 3 A, V <sub>BE</sub> = 3 V, dI <sub>F</sub> /dt = -50 A/µs	_	1.0	_	μs
Reverse recovery charge	Q <sub>rr</sub>		_	8	_	μC

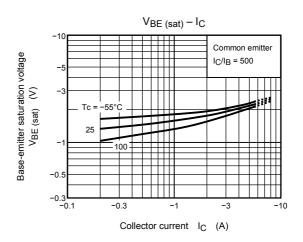




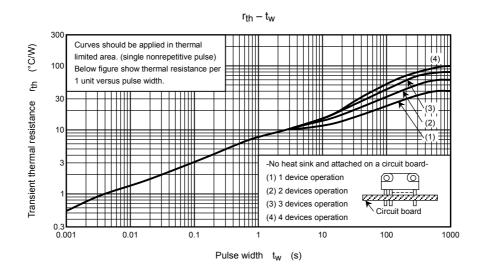


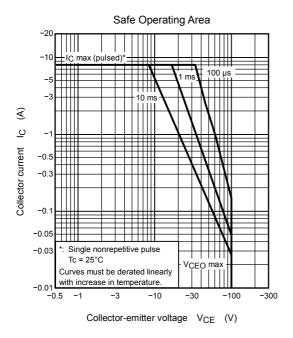


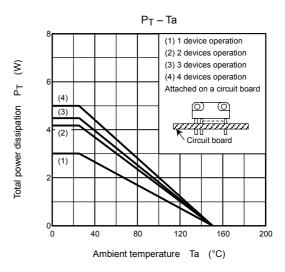


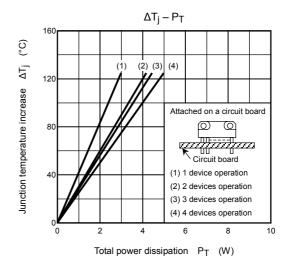


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